

Electronic Materials and Processes for Space (EMPS) Workshop

Tuesday, 1 June 2021

Session 3: Advanced PCB technologies - Virtual (14:30 - 15:20)

-Conveners: Stan Heltzel

time	[id] title	presenter
14:30	[13] High-density PCB technology assessment for space applications	CAUWE, Maarten
14:55	[14] HDI GSTP French consortium	PERNOT , Philippe

Session 3: Advanced PCB technologies - Virtual (15:35 - 16:50)

time	[id] title	presenter
15:35	[15] Reliability of HDI PCBs: Thermo-mechanical simulations	NAWGHANE, Chinmay
16:00	[16] An overview of PCB risks and supplier capability	SOOD, Bhanu
16:25	[17] PCB embedding technologies	STĘPLEWSKI, Wojciech